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Simulation and prediction on phonon thermal conductivity of Al/Cu interface

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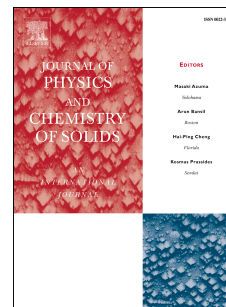
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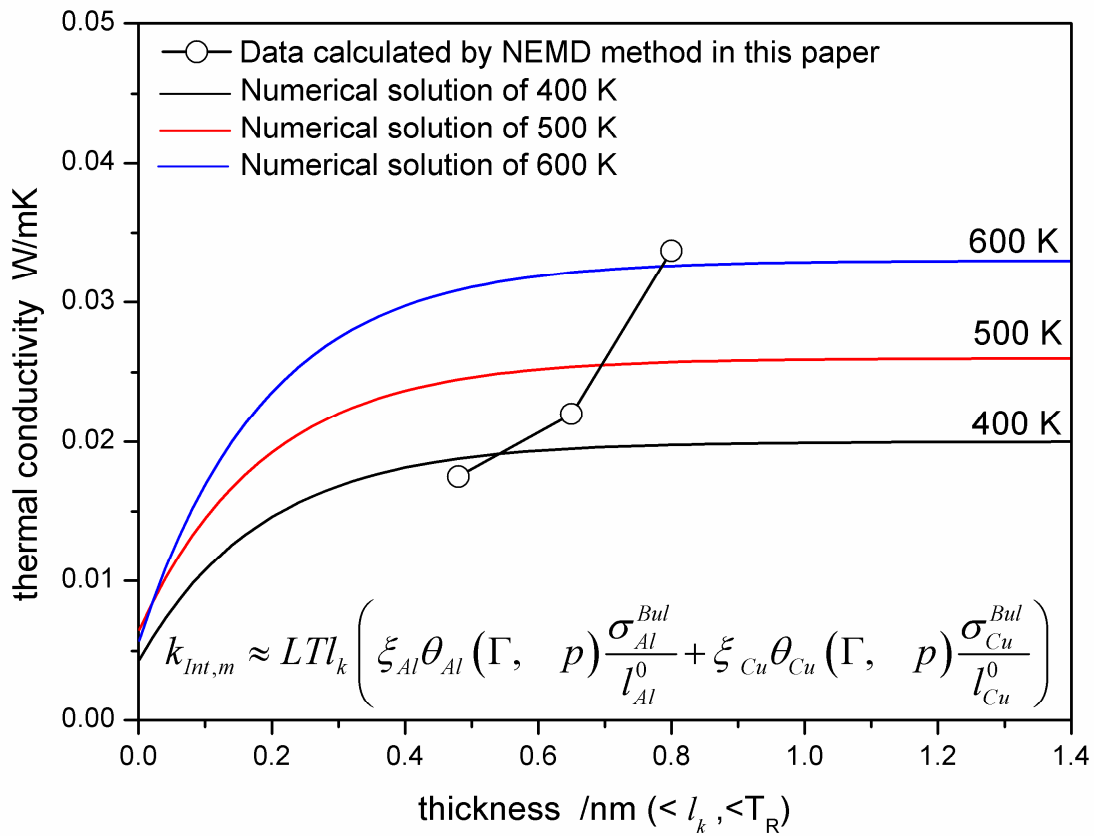
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An approximate mathematical model is proposed to describe the relationship between the phonon thermal conductivity and the thermal conductivities of each thin and bulk materials based on the electrical thermal transport, the free electron approximation, and the Wiedemann-Franz Law. It is helpful for understanding the interface heat transfer mechanism of interface structures, which also implies a potential method for the analysis of thermal performance of interfaces.



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